



30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	Ι _D T _A = +25°C
	760mΩ @ V _{GS} = 4.5V	0.65A
30V	930mΩ @ V _{GS} = 2.5V	0.58A
	1500mΩ @ V _{GS} = 1.8V	0.45A

Description

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Load switch
- Portable applications
- Power Management Functions

Features

- 0.4mm ultra low profile package for thin application
- 0.48mm² package footprint, 16 times smaller than SOT23
- Low V_{GS(th),} can be driven directly from a battery
- Low R_{DS(on)}
- ESD Protected
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

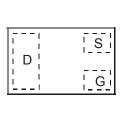
- Case: X2-DFN0806-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 ^{@4}
- Weight: 0.00043 grams (approximate)

ESD PROTECTED

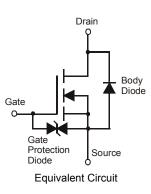


X2-DFN0806-3

Bottom View



Top View Package Pin Configuration



Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN3900UFA-7B	NU	7	8	10,000

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

DMN3900UFA-7B

NU = Product Type Marking Code

Top View Bar Denotes Gate and Source Side



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	30	
Gate-Source Voltage			V _{GSS}	±8	V
		(Note 6)	ID	0.65	
Continuous Drain Current V	V _{GS} = 4.5V	T _A = +70°C (Note 6)		0.52	•
		(Note 5)	ID	0.55	A
Pulsed Drain Current ((Note 7)	I _{DM}	2.5	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Dower Dissinction	(Note 6)	D	490	m)//	
Power Dissipation	(Note 5)	P _D	390	mW	
Thermal Desistance, Junction to Ambient	(Note 6)	6	255	°C/W	
Thermal Resistance, Junction to Ambient	(Note 5)	R _{0JA}	327		
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

			_				
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)				1	1		
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	—	1	μA	V_{DS} = 30V, V_{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	—	3	μA	V_{GS} = ±8V, V_{DS} = 0V	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(th)}	0.45	_	0.95	V	V_{DS} = V_{GS} , I_D = 250 μ A	
			400	760	mΩ	V_{GS} = 4.5V, I _D = 200mA	
Static Drain-Source On-Resistance	R _{DS(on)}	—	480	930		V_{GS} = 2.5V, I_{D} = 100mA	
			617	1500		V _{GS} = 1.8V, I _D = 75mA	
Forward Transfer Admittance	Y _{fs}	40	_		mS	V _{DS} = 3V, I _D = 10mA	
Diode Forward Voltage (Note 8)	V _{SD}		0.7	1.2	V	V _{GS} = 0V, I _S = 300mA	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	—	42.2	—	pF	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz	
Output Capacitance	Coss		4.5		pF		
Reverse Transfer Capacitance	C _{rss}		3,4	_	pF		
Gate Resistance	Rg		468	_	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz	
Total Gate Charge	Qg		0.7	_	nC		
Gate-Source Charge	Q _{gs}		0.11		nC	− V _{GS} = 4.5V, V _{DS} = 15V, − I _D = 200mA	
Gate-Drain Charge	Q _{gd}	-	0.15	_	nC	1B - 20011A	
Turn-On Delay Time	t _{D(on)}		10.5	_	ns		
Turn-On Rise Time	tr	_	7.8	_	ns	$V_{DS} = 10V, I_D = 200mA$ $V_{GS} = 4.5V, R_G = 6\Omega$	
Turn-Off Delay Time	t _{D(off)}	—	80.6	—	ns		
Turn-Off Fall Time	t _f	_	23.4	_	ns	1	

Notes: 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.

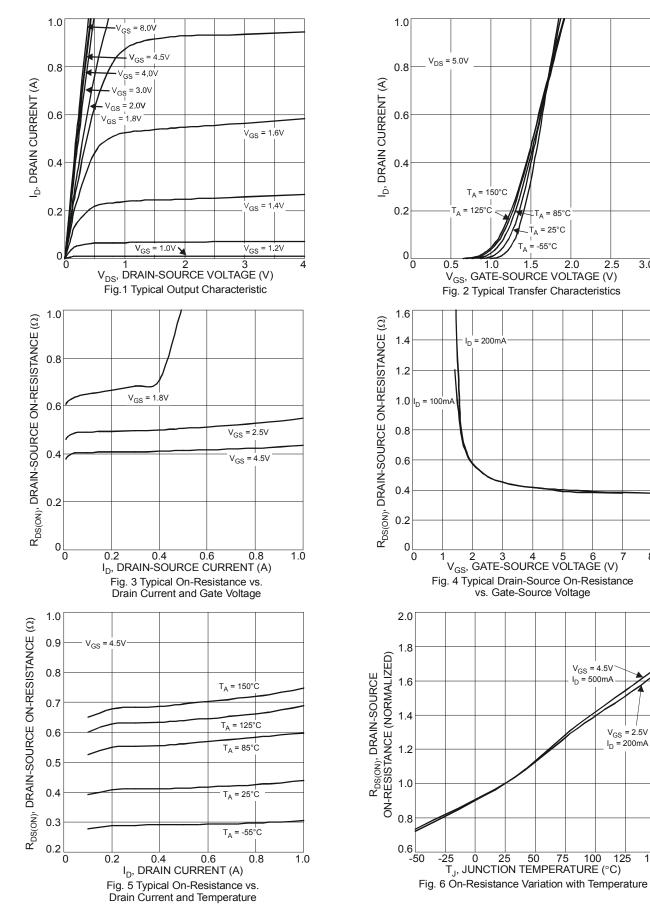
Device mounted on FR-4 PCB, with minimum recommended pad layout.
Device mounted on FR-4 PCB, with minimum recommended pad layout, except the device measured at t ≤ 10 sec.
Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to production testing



DMN3900UFA

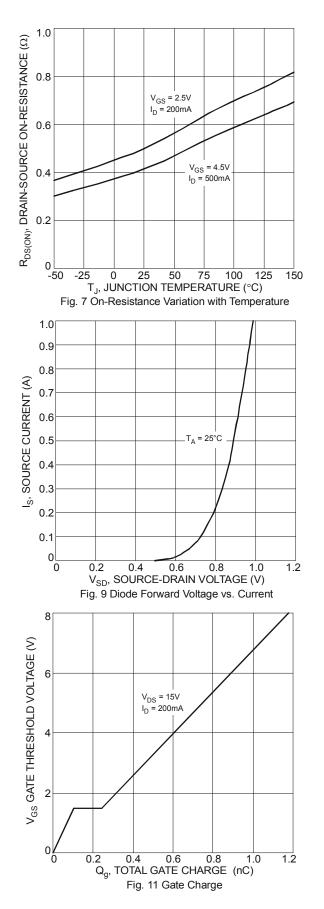
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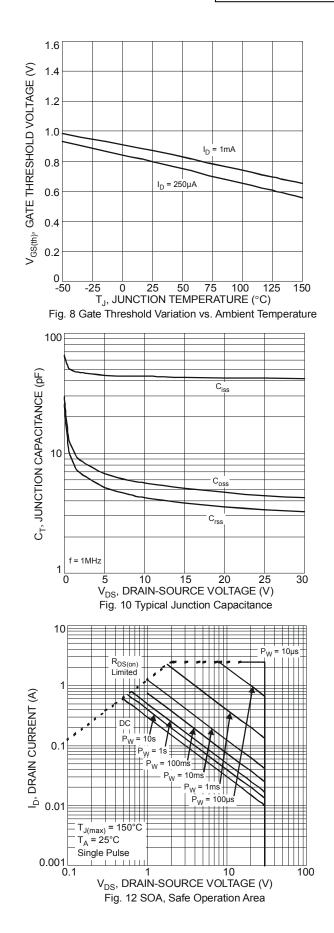
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150

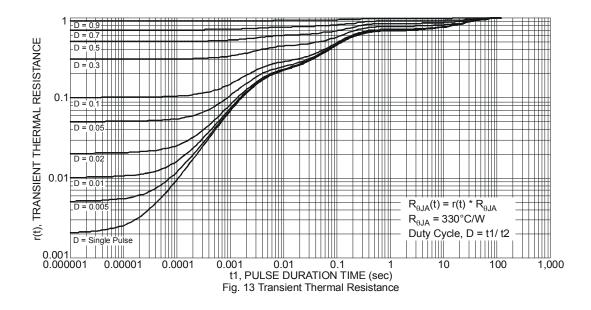






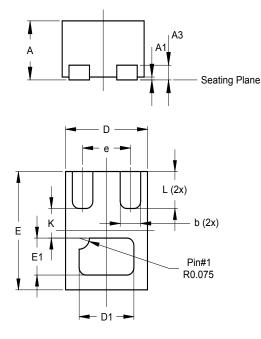
DMN3900UFA Document number: DS35736 Rev. 4 - 2





Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

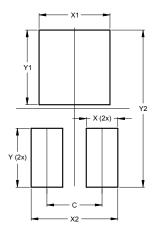


	X2-DFN0806-3						
Dim	Min	Max	Тур				
Α	0.375	0.40	0.39				
A1	0	0.05	0.02				
A3	-	-	0.10				
b	0.10	0.20	0.15				
D	0.55	0.65	0.60				
D1	0.35	0.45	0.40				
Е	0.75	0.85	0.80				
E1	0.20	0.30	0.25				
е	-	-	0.35				
κ	-	-	0.20				
L	0.20	0.30	0.25				
	All Dimensions in mm						



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
С	0.350			
Х	0.200			
X1	0.450			
X2	0.550			
Y	0.375			
Y1	0.475			
Y2	1.000			

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